L Number	Hits	Search Text	DB	Time stamp
3	1	4423701.pn.	USPAT; US-PGPUB	2003/03/04 10:10
4	1	4423701.pn. and (heater or temperature)	USPAT; US-PGPUB	2003/03/04 11:13
5	9	(US-6524952-$ or US-6387185-$ or US-5916365-$ or US-5292554-$ or US-4423701-$ or US-4664939-$).did. or (US-20020197863-$ or US-20020076490-$ or US-20020056414-$).did.	USPAT; US-PGPUB	2003/03/04 13:26
6	2	((US-6524952-$ or US-6387185-$ or US-5916365-$ or US-5292554-$ or US-4423701-$ or US-4664939-$).did. or (US-20020197863-$ or US-20020076490-$ or US-20020056414-$).did.) and aperture	USPAT; US-PGPUB	2003/03/04 13:51
7	0	4423701.pn. and gase	USPAT; US-PGPUB	2003/03/04 13:51
8	1	4423701.pn. and gas	USPAT; US-PGPUB	2003/03/04 13:51
11	1	4664939.pn. and gas	USPAT; US-PGPUB	2003/03/04 14:09
14	2	((US-6524952-$ or US-6387185-$ or US-5916365-$ or US-5292554-$ or US-4423701-$ or US-4664939-$).did. or (US-20020197863-$ or US-20020076490-$ or US-20020056414-$).did.) and electrostatic	USPAT; US-PGPUB	2003/03/04 14:18
15	0	((US-6524952-$ or US-6387185-$ or US-5916365-$ or US-5292554-$ or US-4423701-$ or US-4664939-$).did. or (US-20020197863-$ or US-20020076490-$ or US-20020056414-$).did.) and piston	USPAT; US-PGPUB	2003/03/04 14:18
16	18	atomic adj layer adj deposition and piston	USPAT; US-PGPUB	2003/03/04 14:22
17	437	deposition and chamber and support and wafer and piston	USPAT; US-PGPUB	2003/03/04 14:23
18	242	(deposition and chamber and support and wafer and piston) and region and gas	USPAT; US-PGPUB	2003/03/04 14:23
19	191	((deposition and chamber and support and wafer and piston) and region and gas) and @ad<=20010727	USPAT; US-PGPUB	2003/03/04 14:25
20	94	deposition and wafer adj support and piston	USPAT; US-PGPUB	2003/03/04 14:25
21	83	(deposition and wafer adj support and piston) and @ad<=20010727	USPAT; US-PGPUB	2003/03/04 14:26
22	8	((deposition and wafer adj support and piston) and @ad<=20010727) and wafer adj support with piston	USPAT; US-PGPUB	2003/03/04 14:28
23	1	5228502.pn.	USPAT; US-PGPUB	2003/03/04 14:28
-	498	atomic adj layer adj deposition	USPAT; US-PGPUB	2003/03/03 14:05
-	194	(atomic adj layer adj deposition) and chamber and region$1	USPAT; US-PGPUB	2003/02/27 15:50
-	94	((atomic adj layer adj deposition) and chamber and region$1) and @ad<=20010727	USPAT; US-PGPUB	2003/02/27 16:43
-	67	(((atomic adj layer adj deposition) and chamber and region$1) and @ad<=20010727) and wafer	USPAT; US-PGPUB	2003/02/27 15:51
-	16	((((atomic adj layer adj deposition) and chamber and region$1) and @ad<=20010727) and wafer) and support	USPAT; US-PGPUB	2003/02/27 15:51
-	12	(((((atomic adj layer adj deposition) and chamber and region$1) and @ad<=20010727) and wafer) and support) and heater	USPAT; US-PGPUB	2003/02/27 16:01
-	1	5951776.pn.	USPAT; US-PGPUB	2003/02/27 16:06
-	1	6525747.pn.	USPAT; US-PGPUB	2003/02/27 16:40
-	1	"6174805".PN.	USPAT; US-PGPUB	2003/02/27 16:36

–	1	"6132514".PN.	USPAT; US-PGPUB	2003/02/27 16:36
–	1	"6071552".PN.	USPAT; US-PGPUB	2003/02/27 16:37
–	1	"5998871".PN.	USPAT; US-PGPUB	2003/02/27 16:37
–	1	"5998871".PN.	USPAT; US-PGPUB	2003/02/27 16:37
–	1	"5972785".PN.	USPAT; US-PGPUB	2003/02/27 16:37
–	1	"5916365".PN.	USPAT; US-PGPUB	2003/02/27 16:37
–	1	"5416045".PN.	USPAT; US-PGPUB	2003/02/27 16:38
–	1	"5344792".PN.	USPAT; US-PGPUB	2003/02/27 16:38
–	1	"6190732".PN.	USPAT; US-PGPUB	2003/02/27 16:39
–	1	"6174377".PN.	USPAT; US-PGPUB	2003/02/27 16:39
–	1	"5935338".PN.	USPAT; US-PGPUB	2003/02/27 16:40
–	1	"5879459".PN.	USPAT; US-PGPUB	2003/02/27 16:40
–	1	"5582866".PN.	USPAT; US-PGPUB	2003/02/27 16:40
–	655	700/121.ccls.	USPAT; US-PGPUB	2003/02/27 16:40
–	213	700/121.ccls. and deposition	USPAT; US-PGPUB	2003/02/27 16:41
–	113	(700/121.ccls. and deposition) and chamber	USPAT; US-PGPUB	2003/02/27 16:41
–	90	((700/121.ccls. and deposition) and chamber) and @ad<=20010727	USPAT; US-PGPUB	2003/03/03 14:47
–	3	(((700/121.ccls. and deposition) and chamber) and @ad<=20010727) and piston	USPAT; US-PGPUB	2003/02/27 16:41
–	1	(((atomic adj layer adj deposition) and chamber and region$1) and @ad<=20010727) and piston	USPAT; US-PGPUB	2003/02/27 16:50
–	1228	118/719.ccls.	USPAT; US-PGPUB	2003/02/27 16:50
–	55	118/719.ccls. and wafer and piston	USPAT; US-PGPUB	2003/02/27 16:50
–	16	(118/719.ccls. and wafer and piston) and aperture	USPAT; US-PGPUB	2003/02/27 16:51
–	15	kosowski.xa.	USPAT; US-PGPUB	2003/03/03 14:05
–	4183	deposition and wafer and support and chamber and region$2 and temperature and two and gas	USPAT; US-PGPUB	2003/03/03 14:47
–	3626	(deposition and wafer and support and chamber and region$2 and temperature and two and gas) and @ad<=20010727	USPAT; US-PGPUB	2003/03/03 17:34
–	167	((deposition and wafer and support and chamber and region$2 and temperature and two and gas) and @ad<=20010727) and piston	USPAT; US-PGPUB	2003/03/03 14:50
–	11	(((deposition and wafer and support and chamber and region$2 and temperature and two and gas) and @ad<=20010727) and piston) and monolayer	USPAT; US-PGPUB	2003/03/03 14:51
–	90	((deposition and wafer and support and chamber and region$2 and temperature and two and gas) and @ad<=20010727) and atomic adj layer	USPAT; US-PGPUB	2003/03/03 14:51
–	1413684	(((deposition and wafer and support and chamber and region$2 and temperature and two and gas) and @ad<=20010727) and atomic adj layer) and deposition near$5 region$1	USPAT; US-PGPUB	2003/03/03 14:53

–	90	(((deposition and wafer and support and chamber and region$2 and temperature and two and gas) and @ad<=20010727) and atomic adj layer) and (deposition near$5 region$1)	USPAT; US-PGPUB	2003/03/03 16:18
–	1		USPAT; US-PGPUB	2003/03/03 15:11
–	1		USPAT; US-PGPUB	2003/03/03 15:11
–	1		USPAT; US-PGPUB	2003/03/03 15:11
–	1		USPAT; US-PGPUB	2003/03/03 15:11
–	4	((deposition and wafer and support and chamber and region$2 and temperature and two and gas) and @ad<=20010727) and moveable adj support	USPAT; US-PGPUB	2003/03/03 16:35
–	64	deposition and moveable adj support	USPAT; US-PGPUB	2003/03/03 16:35
–	62	(deposition and moveable adj support) and @ad<=20010727	USPAT; US-PGPUB	2003/03/03 16:37
–	25	((deposition and moveable adj support) and @ad<=20010727) and wafer	USPAT; US-PGPUB	2003/03/03 17:16
–	1		USPAT; US-PGPUB	2003/03/03 16:45
–	1		USPAT; US-PGPUB	2003/03/03 16:45
–	1		USPAT; US-PGPUB	2003/03/03 16:46
–	1		USPAT; US-PGPUB	2003/03/03 16:46
–	655	700/121.ccls.	USPAT; US-PGPUB	2003/03/03 17:16
–	2	700/121.ccls. and atomic adj layer adj deposition	USPAT; US-PGPUB	2003/03/03 17:33
–	21	interconnected with deposition with region$2	USPAT; US-PGPUB	2003/03/03 17:33
–	21	(interconnected with deposition with region$2) and @ad<=20010727	USPAT; US-PGPUB	2003/03/04 10:10